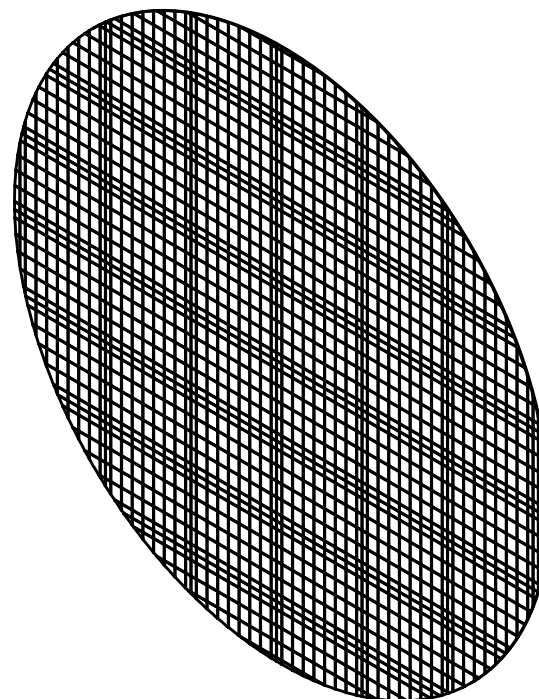
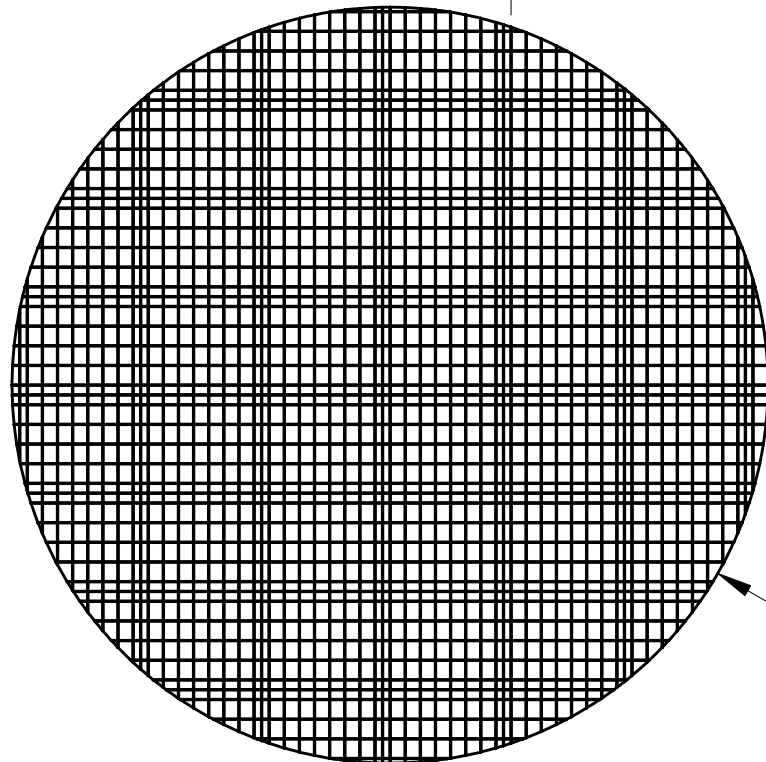


2

1



Reticle Size: 32mm x 26mm  
Wafer Size: 200mm

32



Ø200



UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN MILLIMETERS  ANGULAR = ± °  SURFACE FINISH   DO NOT SCALE DRAWING  BREAK ALL SHARP EDGES AND REMOVE BURRS  THIRD ANGLE PROJECTION 		NAME	DATE	TITLE  wafer.space Wafer Dicing Schema Run 1 GF180MCU					
	DRAWN	ANDREW WINGATE	09/21/2025				SIZE	DWG NO.	REV.
	CHECKED						A		
	APPROVED			SCALE	1:2	WEIGHT	SHEET	1 of 7	
		MATERIAL	FINISH						

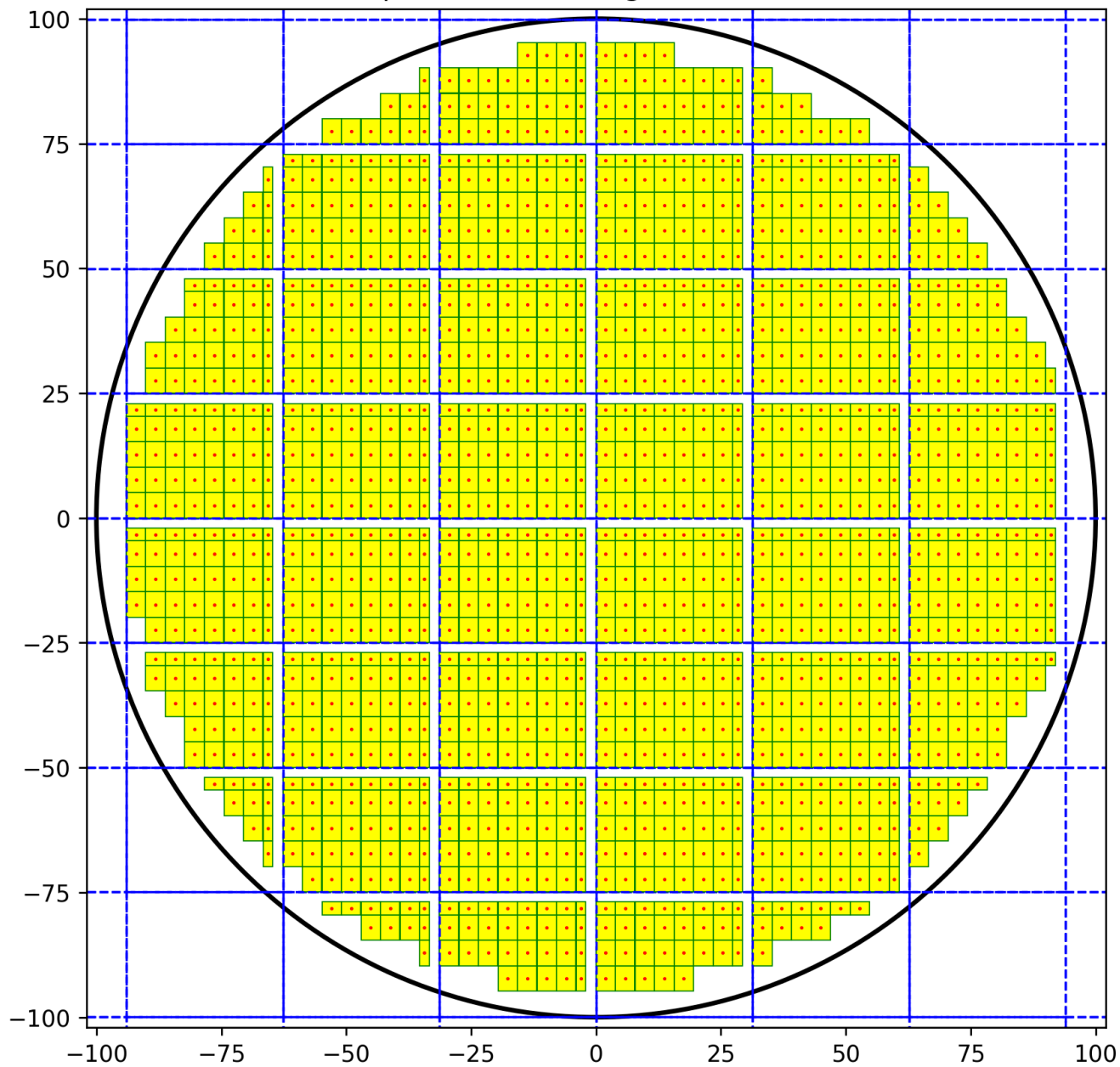
2

1

2

1

200mm Wafer Map: 1934 full dies (green) + reticles (blue dashed)



B

A

2

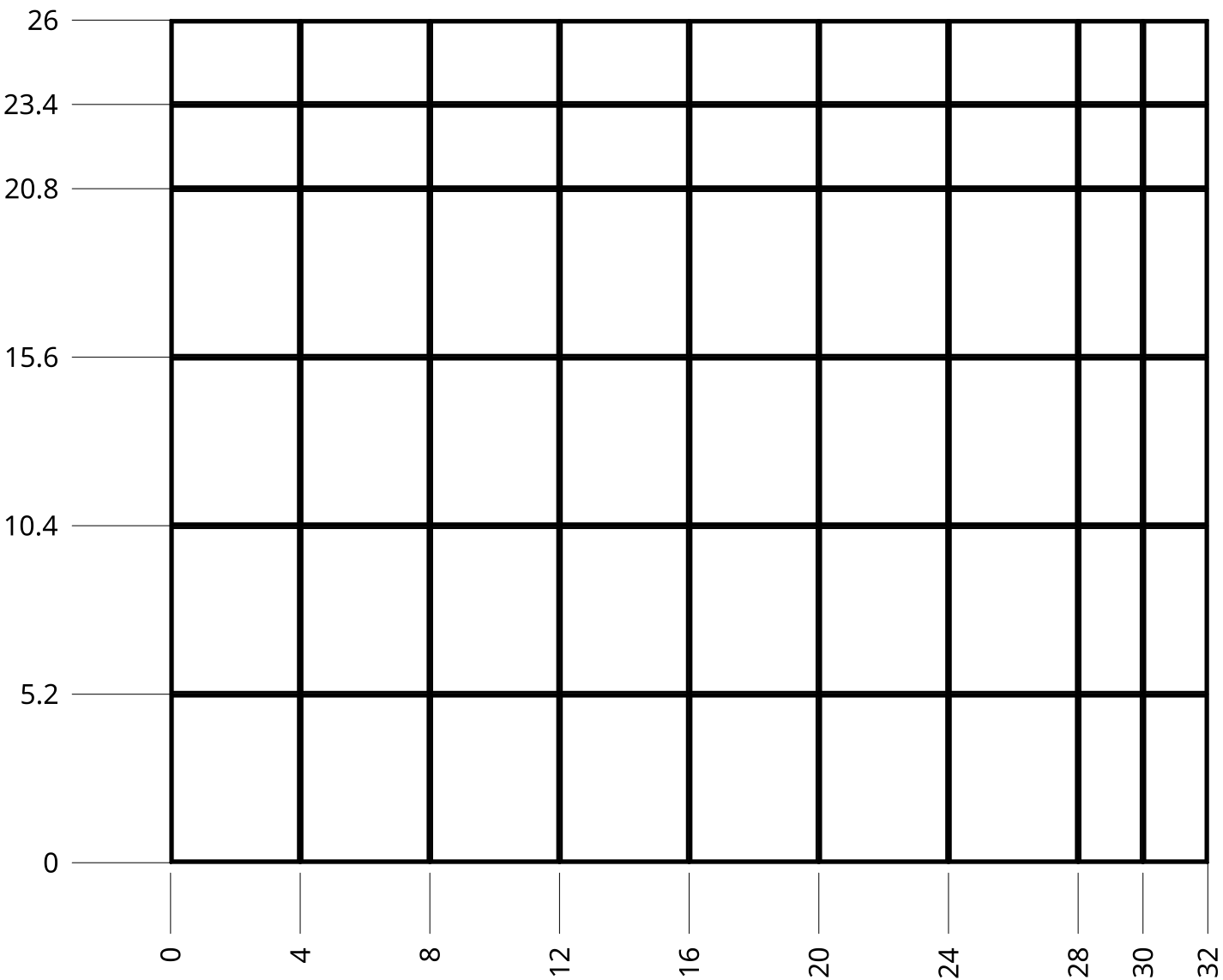
1

B

A

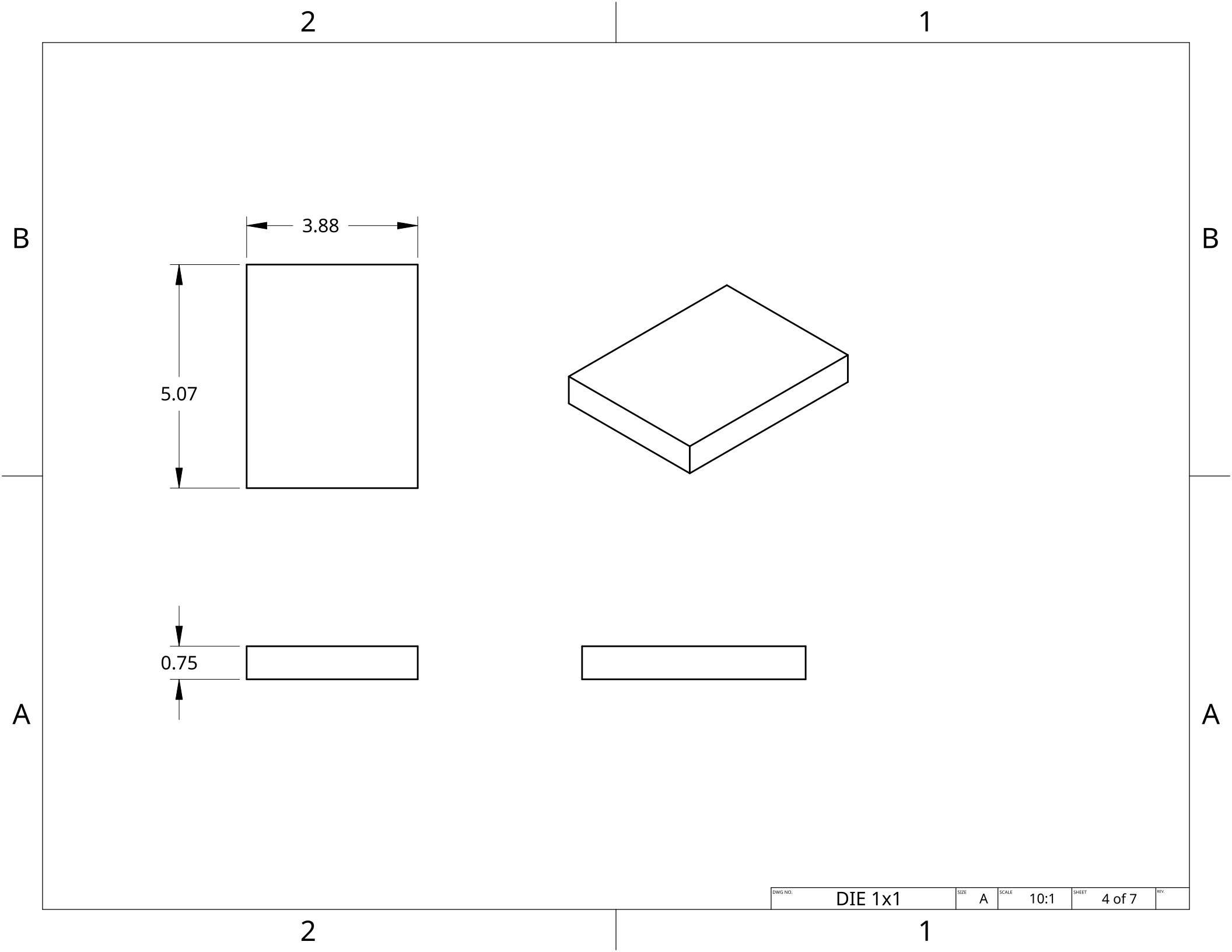
B

A



Note: Dimensions are cut centerlines

DWG NO.	SINGLE_RETICLE	SIZE	A	SCALE	5:1	SHEET	3 of 7	REV.	
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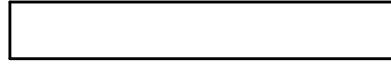
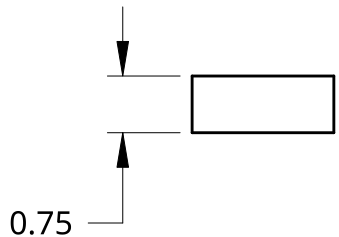
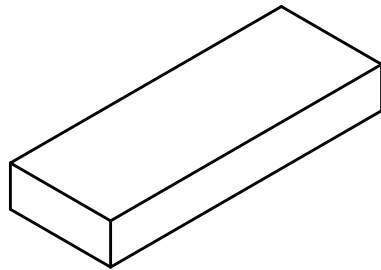
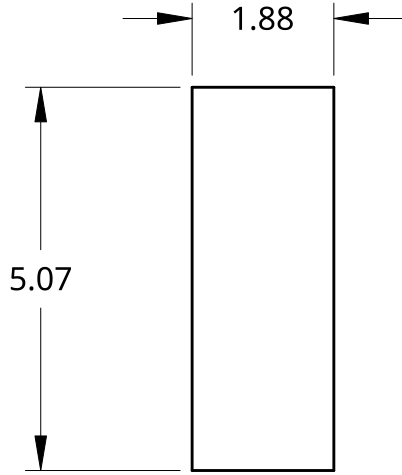


B

A

B

A

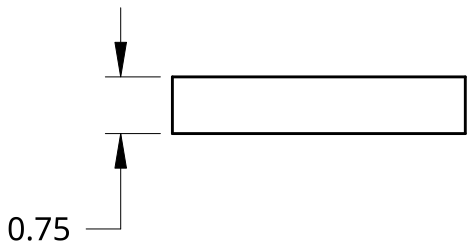
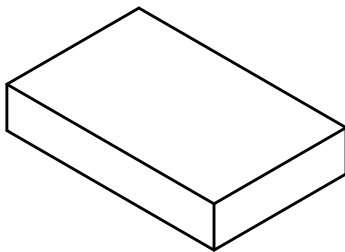
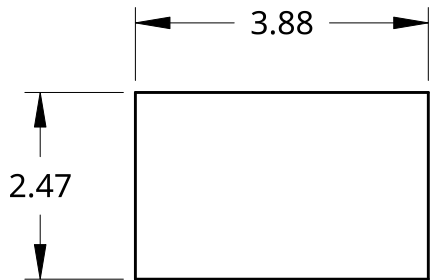


B

B

A

A

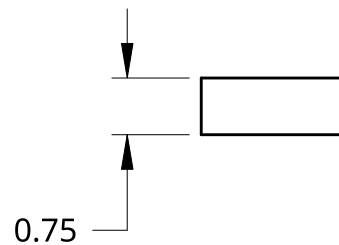
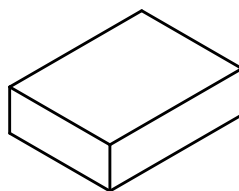
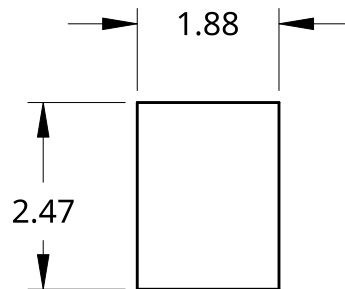


2

1

B

B



A

A

2

1

DWG NO.	DIE_05X05	SIZE	A	SCALE	10:1	SHEET	7 of 7	REV.	
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